

Appl. No. 10/683,764
Amdt. dated Sep. 9, 2005
Reply to Office action of Mar. 9, 2005

Amendments to the Abstract:

Please replace the Abstract with the following rewritten paragraph:

[0030] The present ~~disclosure~~ invention provides a method and system for implanting a piece of wood or wood composite to improve the electrostatic attraction thereupon. A method is provided for treating a lignocellulosic substrate such as medium density fiberboard (MDF). The method includes implanting a conductive material into the lignocellulosic substrate, pre-heating the implanted lignocellulosic substrate, coating the pre-heated implanted lignocellulosic substrate with a powder solution, and curing the powder coated substrate.